

Build Up HDI (Standard)		12 - Layers	
HDI12_1+10b+1_1,45_17.5_engl		Core: 0,15 mm Cu 17.5/17.5 µm	
WE-Article No.:		1 + 10B + 1	
Customer:			

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE					[µm]	[µm]	
	TOP/VS			Foil	12 µm ¹⁾		12	
						1 x 1080	60	
	2			Foil	9 µm		30	
						1 x 1080	66	
	3				17.5 µm		16	
				0,150 mm			150	
	4				17.5 µm		16	
						2 x 1080	134	
	5				17.5 µm		16	
				0,150 mm			150	
	6				17.5 µm		16	
					2 x 1080	134		
	7			17.5 µm		16		
			0,150 mm			150		
	8			17.5 µm		16		
					2 x 1080	134		
	9			17.5 µm		16		
			0,150 mm			150		
	10			17.5 µm		16		
					1 x 1080	66		
	11		Foil	9 µm		30		
					1 x 1080	60		
	BOT/RS		Foil	12 µm ¹⁾		12		
1) copper thickness outer layers: appr. 55 µm								
total material thickness:						1466		
<small>Note: Lamination thickness for Prepregs depending on layout characteristics.</small>								

final lamination thickness:	1,45	+/-	0,11	mm	Date:	Engineer:
thickness with electro plated Cu:	1,54	+/-	0,14	mm		
total thickness with soldermask	1,60	+/-	0,16	mm		
customer requirement		+/-		mm	point:	
prepared: on	by	checked: on	by	approved: on	by	revision
29.03.2006	S. Keller	04.05.2006	M.Kress	04.05.2006	R.Schönholz	00
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